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PATENT ABSTRACTS OF JAPAN

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(71)Applicant : MATSUSHITA ELECTRIC IND CO LTD

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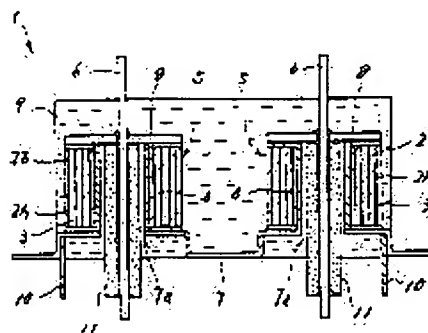
(72)Inventor : YOSHINO HIRONORI

(54) THROUGH-TYPE HIGH-VOLTAGE CAPACITOR

(57)Abstract:

PURPOSE: To prevent breakdown strength characteristic from deteriorating even after repeated thermal stress during a heat cycle by a method wherein a capacitor device where a plastic film sandwiched between two electrodes has been wound on the internal circumference of a winding spool is fixed to a conductor plate and an insulator is filled in the neighborhood of the plate so that the conductor plate can be fixed by using the insulator.

CONSTITUTION: A cylindrical capacitor device 5 is provided in such a way that at least one plastic film 3 is sandwiched between two electrodes 2A, 2B and that the film is wound on the external circumference of a winding spool 4. A through-type conductor 6 is installed in such a way that it pierces through a hollow part of the winding spool 4 of the capacitor device 5. One electrode 2A of the capacitor device 5 is connected electrically to a lower-part conductor plate 7 and is fixed to it. The other electrode 2B which has been extracted from an upper end of the capacitor device 5 is connected electrically to an upper-part conductor plate 8 and is fixed to it; the upper-part conductor plate 8 is also connected electrically to the through-type conductor 6 and is fixed to it. An insulator 9 such as an epoxy resin or the like is filled in the neighborhood of the upper-part and the lower part conductor plates 8, 7 to form an external package; an external case 10 is attached to the rear surface of the lower-part conductor plate 7, and the insulation between the through-type conductor 6 and the lower-part conductor plate 7 is reinforced.



LEGAL STATUS

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